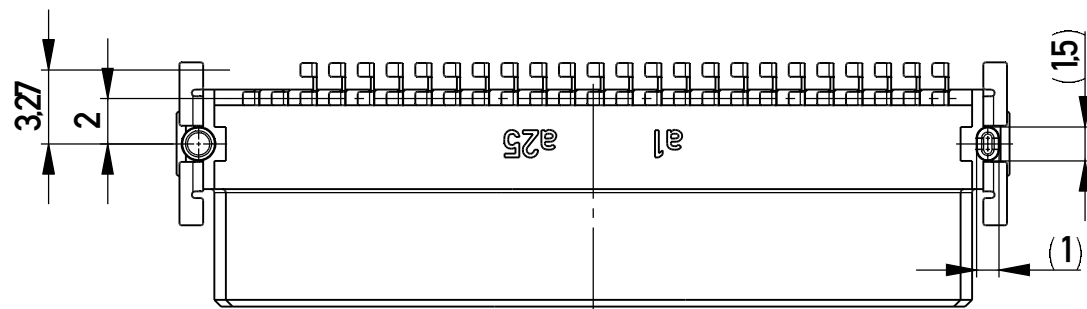
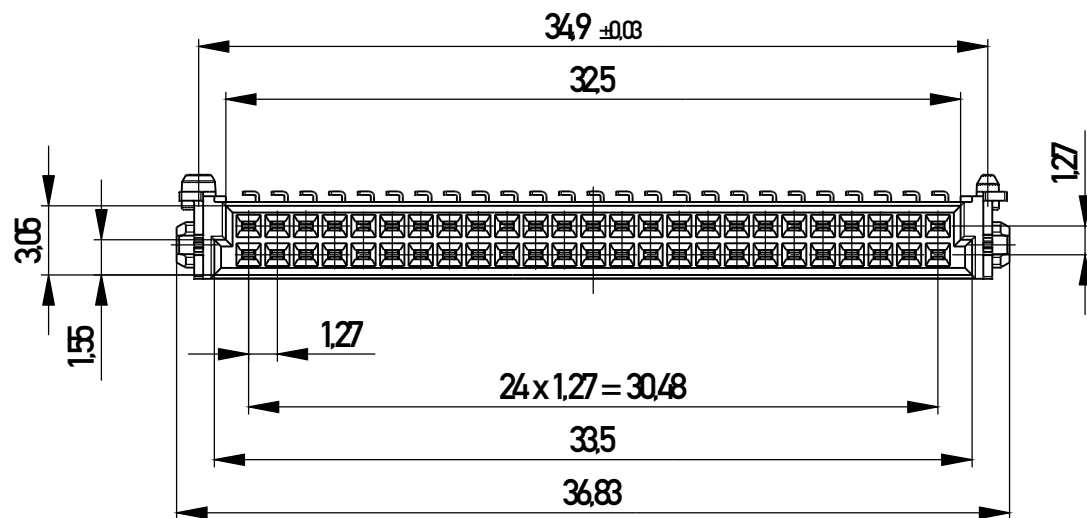
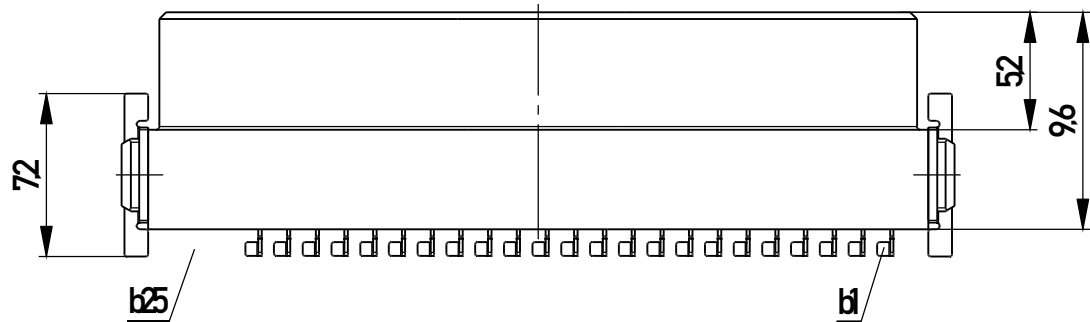
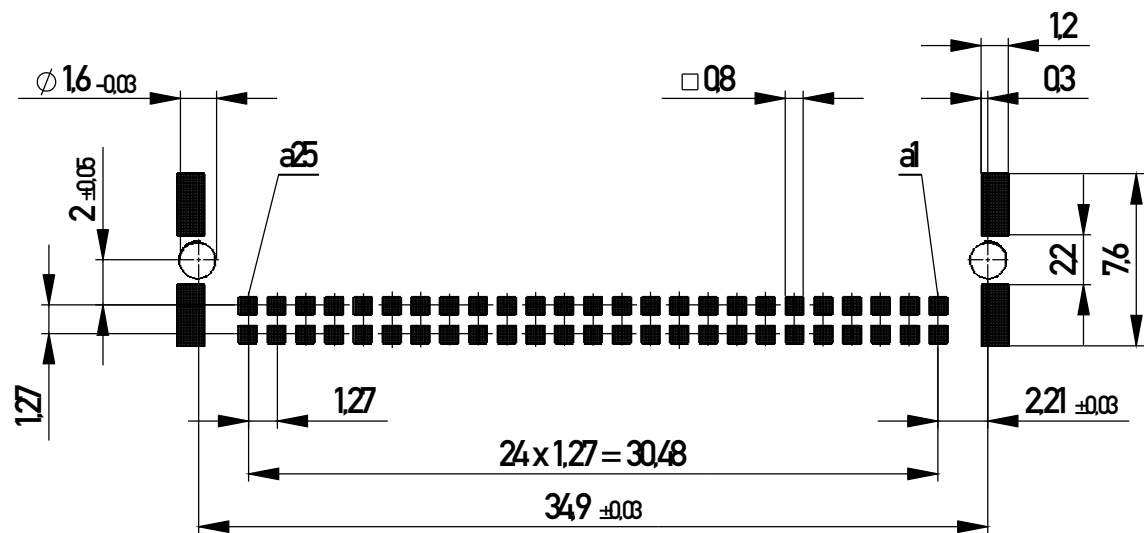
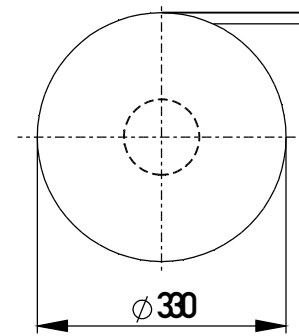


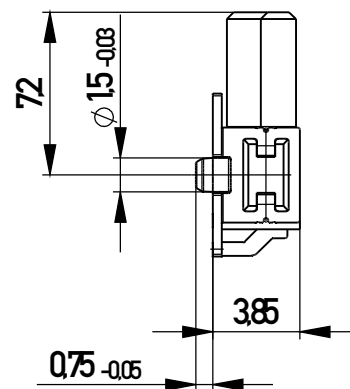
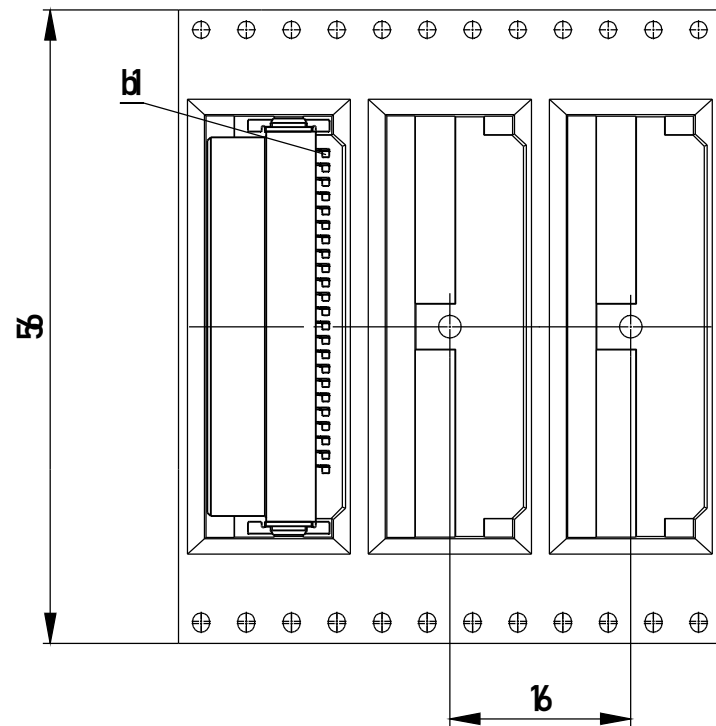
Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



Verpackt im Gurt nach DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 560 Stück
Packaging unit: 560 pcs



Abspulrichtung - Reel off Direction



Anforderungsstufe 1
Performance Level 1

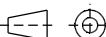
Kontaktbereich vergoldet
Mating Area gold plating

Anschlussbereich verzinkt 4-6 μ m
Terminal Area 4-6 μ m tin plating

Koplanarität der Anschlüsse ≤ 0.1 mm
Coplanarity Area of Termination ≤ 0.1 mm

BA7-03 - Standard Bauhöhe
type7-03 - Standard Assembly Height

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Information: in ESD Beutel verpackt <i>packed in ESD bags</i>				Tolerances		 All Dimensions in mm		Scale 3:1	
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						394396			
c		23.04.2014				www.ERNI.com		K A3	
Index		Date							
						Class SMD			